

TPACK's P-OCKET Family of OTN Mappers Now Available for Demonstration and Evaluation

Copenhagen, Denmark – October 14, 2009, – TPACK (www.TPACK.com), an industry leading provider of cutting-edge silicon ICs that provide core data transport and switching functions to leading telecom and networking equipment suppliers, today announced at SUPERCOMM 2009 (booth #5018) that the P-OCKET family of OTN mappers is ready for demonstration and evaluation on TPACK's reference system, 'Springbank'.

The P-OCKET family is designed to address the stringent performance and reliability requirements of Optical Transport applications (e.g. MSPPs, MetroWDM, P-OTN and Carrier Ethernet Transport) and enables early market introduction of new OTN mapping and networking features at a competitive cost. For instance, the TPACK TPO124 is the only standard product in the market that supports ODU0 mapping, protection and cross connection capabilities.

TPACK's P-OCKET OTN Mappers are based upon the company's SOFTSILICON concept which enable telecom equipment manufacturers to build systems faster and with lower risk, while allowing new functionality to be added during development and out in the field.

"Our solution will be deployed in networks this calendar year by a Tier1 Telecom Equipment Manufacturer that values the addition of GE over ODU0 mapping as a feature to be included in their product releases," explained Thomas Rasmussen, TPACK's Vice President of Product Line Management. "TPACK delivers this capability within months of the standard being approved by the ITU-T."

"TPACK expertise combined with our fast time-to-market advantages and ability to deliver these critical system capabilities on a very compressed schedule, is what positioned us to partner with this customer" elaborated Rasmussen. "We continue to react rapidly to the new OTN standards that are an integral part of implementing the solutions that facilitate the Packet-Optical Evolution."

About P-OCKET OTN Mappers

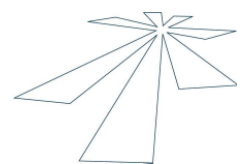
The P-OCKET devices are suited for both new OTN cross connect systems as well as traditional Muxponder-based systems and will support line rates from 2.5G (OTU1) to 100G (OTU4). P-OCKET supports efficient and transparent mapping of any client (packet or TDM) into OTN including GE into ODU0 and STM-1/4, OC-3/12 into subrate ODU1 containers. The most important competitive advantages is the support for ODU0 along with the lower cost option compared to the ASSP when superset features are not all needed.

TPO124 features:

- 2.5G – 10G OTN Mapper
- 1 x OTU2 and 2 x OTU1 line/tributary interfaces
- 8 x tributary
- Efficient mapping of low rate clients to OTN
- OTN Cross connects for sub-wavelength networking

For complete information on the TPACK P-OCKET family visit:

<http://www.tpack.com/products-and-solutions/smartpack-products/P-OCKET-OTN-Mappers.html>



Meet TPACK at SUPERCOMM in Chicago, October 21-23, booth #5018.

For additional information, or to book a meeting with TPACK during SUPERCOMM, please contact:

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About TPACK

TPACK delivers cutting edge Silicon ICs providing core data transport and switching functions to leading Telecom and Networking equipment suppliers. TPACK's SOFTSILICON products support the fastest deployment of new Carrier Class Packet and Optical Network standards, providing the most flexible, cost and power effective implementations throughout the life of the equipment. TPACK's customer base includes Tier 1 equipment providers who account for more than 50% of the optical transport equipment market. TPACK is a privately held company headquartered in Copenhagen, Denmark with offices in Palo Alto, California. For more information, visit www.tpack.com.

